

Bumped GaAs SP3T Switch for WLAN 1.0 - 4.0 GHz

Rev. V2

Features

- 802.11b/g and Bluetooth Applications
- Low Insertion Loss:
0.5 dB 2.4 GHz to 2.5 GHz band
- High Isolation: 32 dB Typical on R_x
- Low Harmonics: <-70 dBc @ 20 dBm
- Flip-chip configuration
- RoHS* Compliant

Description

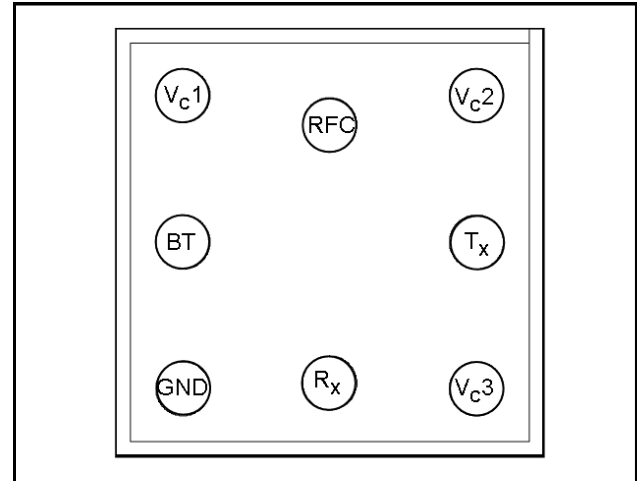
The MASW-009276-001DIE is a bumped GaAs pHEMT MMIC SP3T switch. Typical applications are WLAN (802.11 b/g) and Bluetooth applications.

The MASW-009276-001DIE delivers high isolation, low insertion loss, and high linearity at 2.4 - 2.5 GHz. This device is fabricated using a 0.5 micron gate length GaAs pHEMT process. The process features full passivation for performance and reliability. This die features SnAg(3.5%)Cu(1%) solder bumps for Wafer Level Chip Scale Package (WLCSP) applications.

Ordering Information

Part Number	Package
MASW-009276-001D3K	Die in 3000 piece reel
MASW-009276-002SMB	Sample Board SP3T

Die Bump Pad Layout (bump side up)



Die Bump Pad Configuration

Name	Description
Vc1	Voltage Control 1
BT	Blue Tooth T_x/R_x Port
GND	Ground
R_x	2.5 GHz R_x Port
Vc3	Voltage Control 3
T_x	2.5 GHz T_x Port
Vc2	Voltage Control 2
RFC	Antenna Port

Absolute Maximum Ratings ^{1,2}

Parameter	Absolute Maximum
Input Power @ 3 V Control	+32 dBm
Input Power @ 5 V Control	+35 dBm
Operating Voltage	+8 volts
Operating Temperature	-40°C to +85°C
Storage Temperature	-65°C to +150°C

1. Exceeding any one or combination of these limits may cause permanent damage to this device.
2. M/A-COM Technology does not recommend sustained operation near these survivability limits.

* Restrictions on Hazardous Substances, European Union Directive 2002/95/EC.

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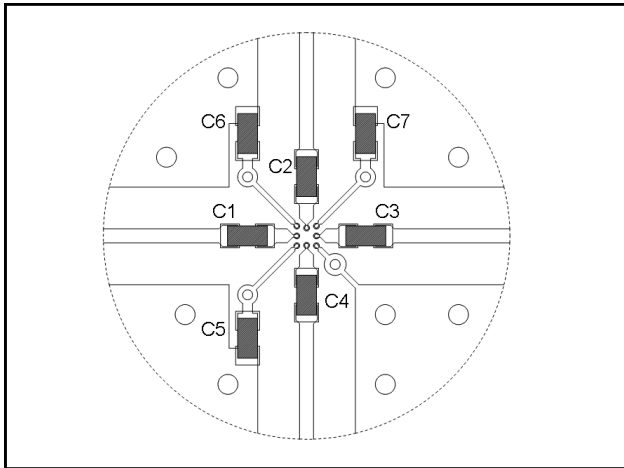
Rev. V2

Electrical Specifications³: $T_A = 25^\circ\text{C}$, $Z_0 = 50\ \Omega$, $V_c = 0\ \text{V} / 3\ \text{V}$, $\text{Pin} = 0\ \text{dBm}$

Parameter	Test Conditions	Units	Min.	Typ.	Max.
Insertion Loss	RFC to Tx/Rx/BT, 2.4 GHz	dB	—	0.5	0.75
Isolation	RFC to Tx, 2.4 GHz	dB	20	24	—
	RFC to Rx, 2.4 GHz	dB	30	32	—
	RFC to BT, 2.4 GHz	dB	20	24	—
Return Loss	2.4 - 2.5 GHz	dB	—	15	—
IP3	RFC to Tx/Rx/BT, 2.4 GHz, 20 dBm Total Power, 1MHz Spacing	dBm	—	55	—
Input P1dB	RFC to Tx, 2.4 GHz	dBm	—	32	—
	RFC to Rx, 2.4 GHz	dBm	—	28	—
	RFC to BT, 2.4 GHz	dBm	—	32	—
Harmonics	RFC to Tx 2.4 GHz, 20 dBm	dBm	—	-75	—
Switching Speed	50% control to 90% RF	ns	—	165	—
	50% control to 10% RF	ns	—	25	—
Control Current	$ V_c = 3\ \text{V}$	μA	—	<1	10

3. External blocking capacitors on all RF ports.

Recommended PCB Configuration



Parts List

Part	Value	Case Style
C1 - C4	39 pF	0402
C5 - C7	1000 pF	0402

Truth Table^{4,5,6}

V_{c1}	V_{c2}	V_{c3}	RFC-BT	RFC-T _x	RFC-R _x
1	0	0	On	Off	Off
0	1	0	Off	On	Off
0	0	1	Off	Off	On

- For positive voltage control, external DC blocking capacitors are required on all RF ports.
- Differential voltage, $V(\text{state } 1) - V(\text{state } 0)$, must be +2.7 V minimum and must not exceed +5 V.
- $0 = 0 \pm 0.3\ \text{V}$, $1 = +2.7\ \text{V}$ to $+5\ \text{V}$.

Handling Procedures

Please observe the following precautions to avoid damage:

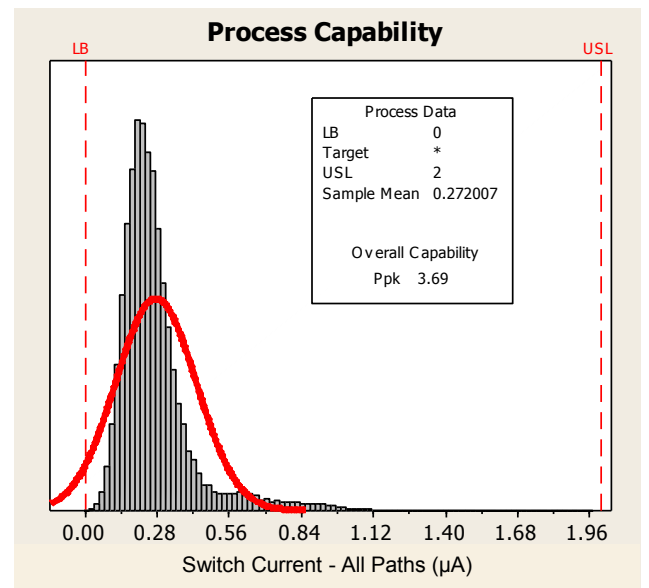
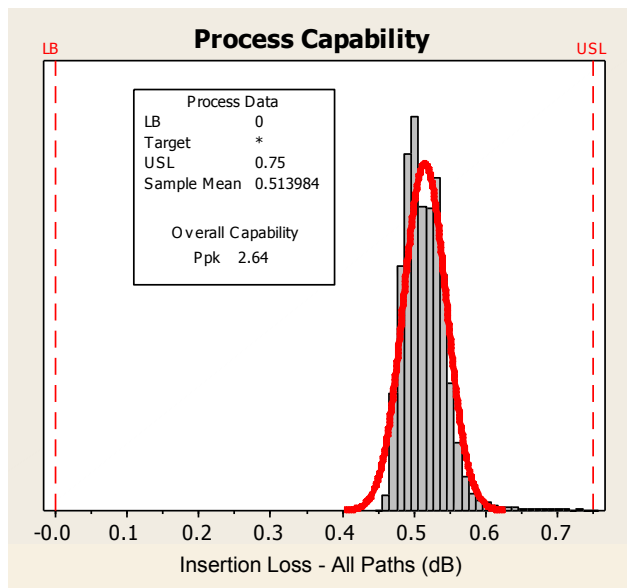
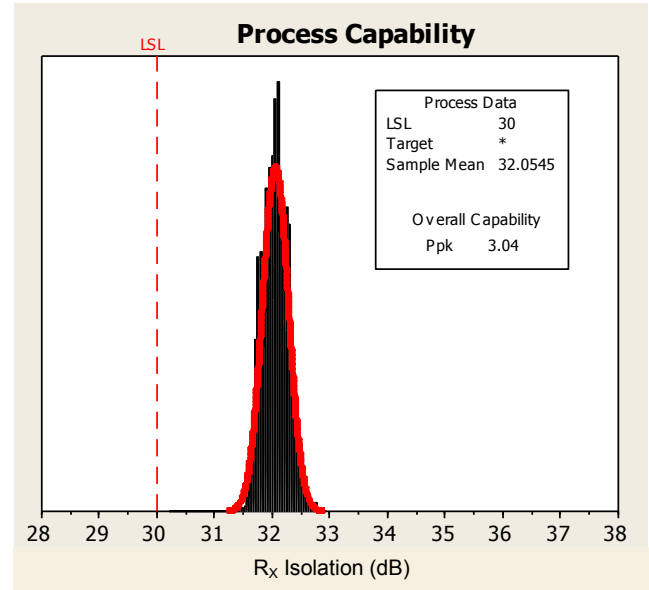
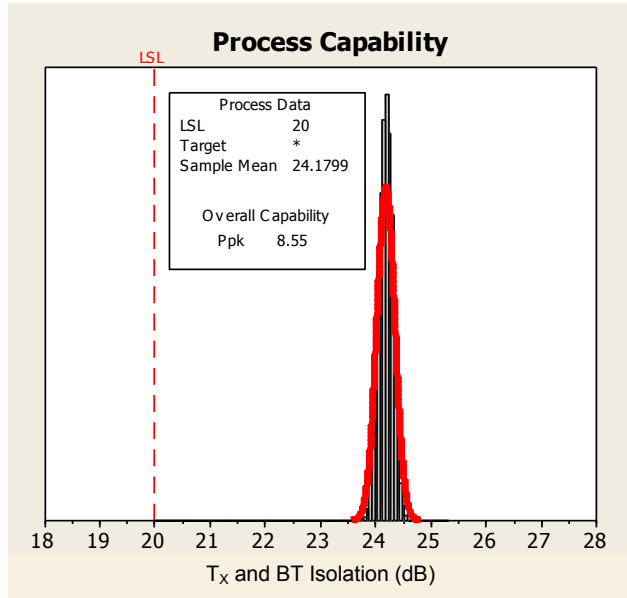
Static Sensitivity

Gallium Arsenide Integrated Circuits are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices.

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Rev. V2

Product Consistency Distribution Charts⁷ (on wafer RF test)



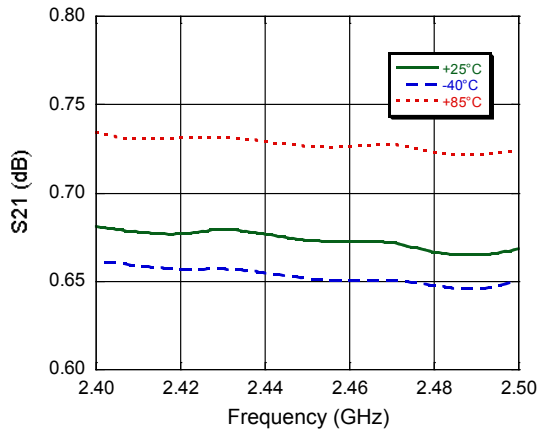
7. Represents >5 wafers, tested per electrical specifications, probed directly on the die to the solder bump: T_A = 25°C, Z₀ = 50 Ω, V_C = 0/3V, P_{IN} = 0 dBm

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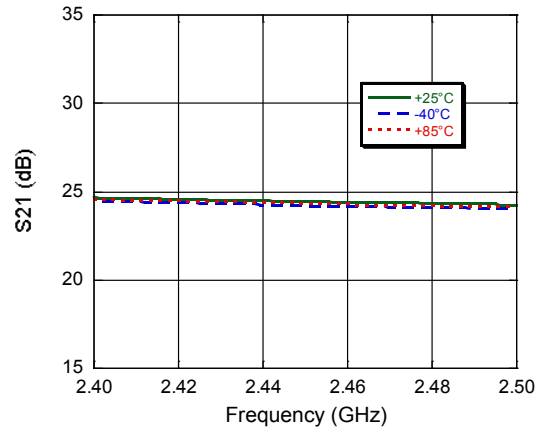
Rev. V2

Typical Performance Curves (plots = chip on board assembly)

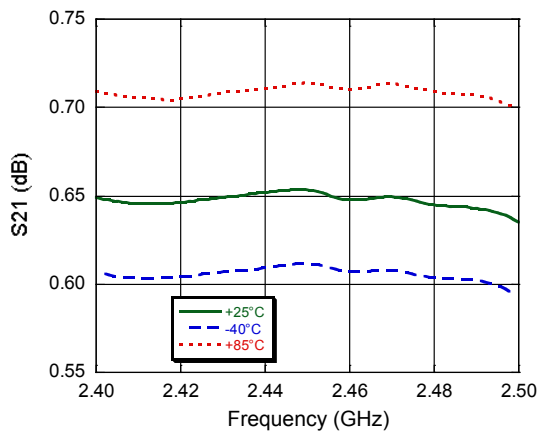
T_X Insertion Loss



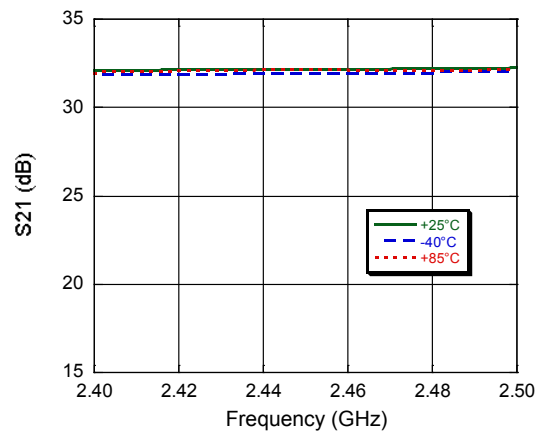
T_X Isolation



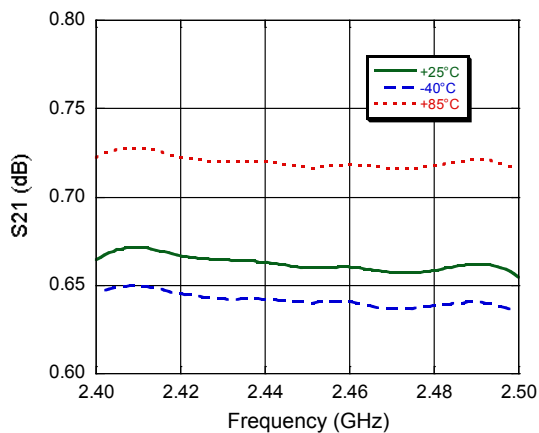
R_X Insertion Loss



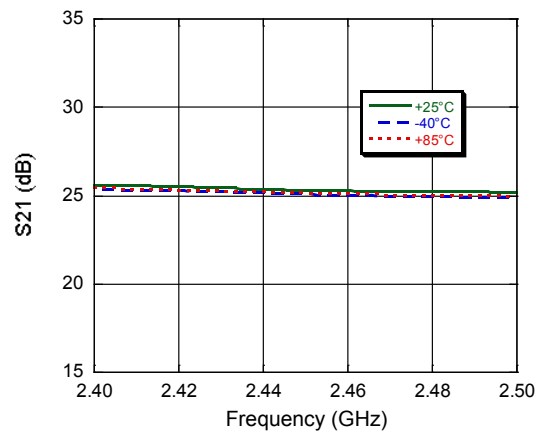
R_X Isolation



BT Insertion Loss



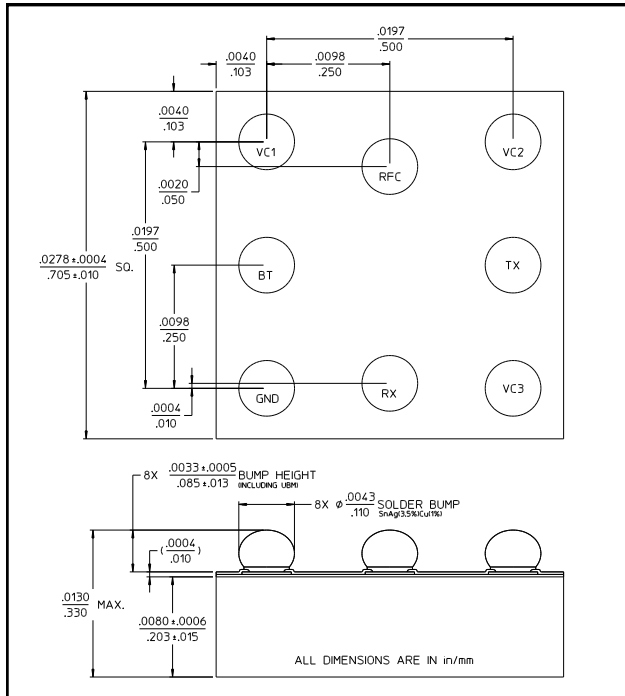
BT Isolation



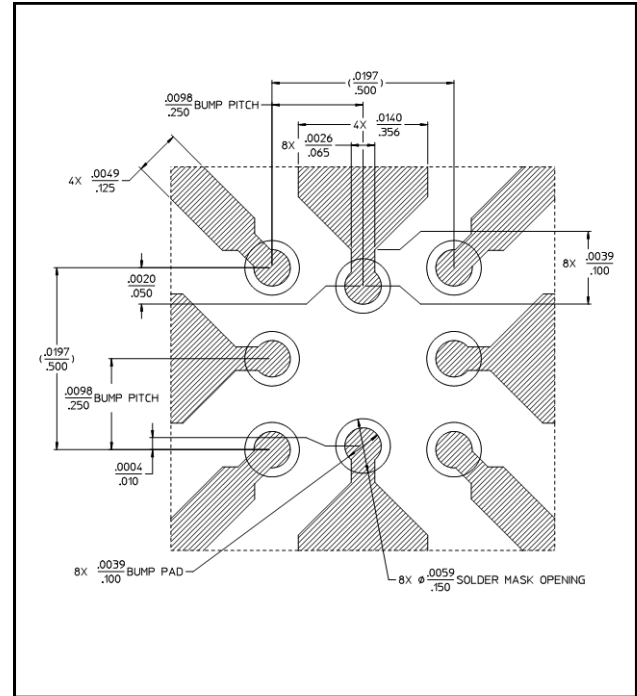
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Rev. V2

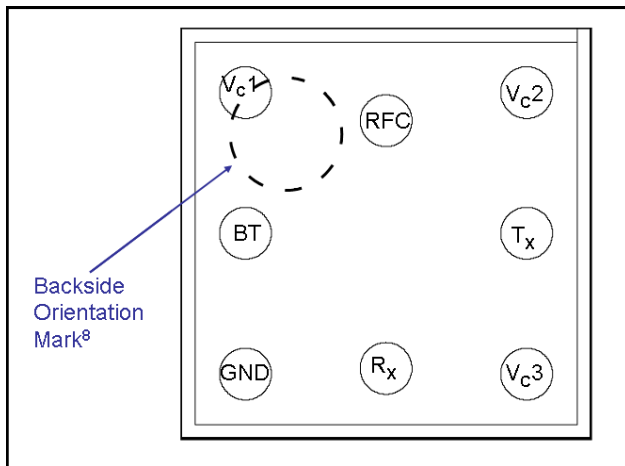
Die Dimensions (Top and Side Views)



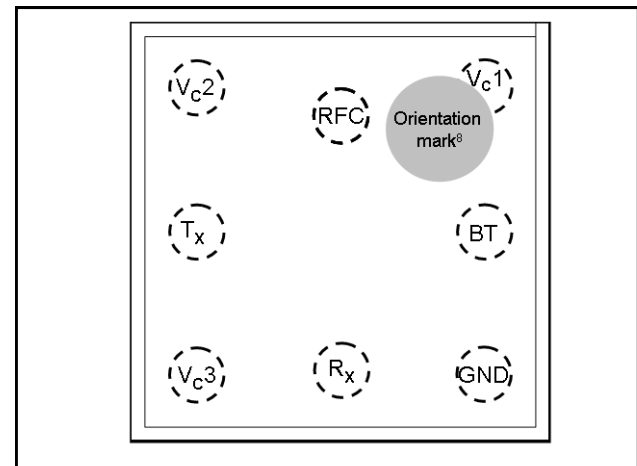
PCB Top Metal / Solder Mask



Die Bump Pad Layout - Top View (bump side up)



Die Bump Pad Layout - Bottom View (bump side down - as installed on board)



8. Orientation mark is only on material that is shipped in tape and reel. The mark is not available on die shipped on grip ring.

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